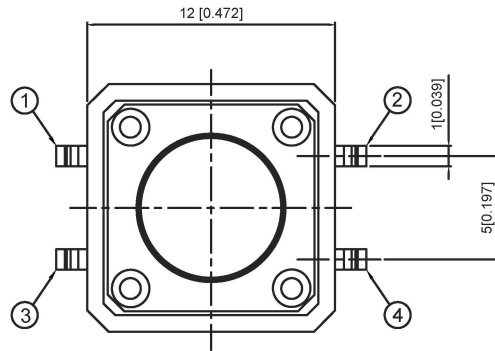
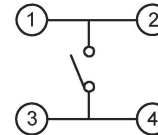
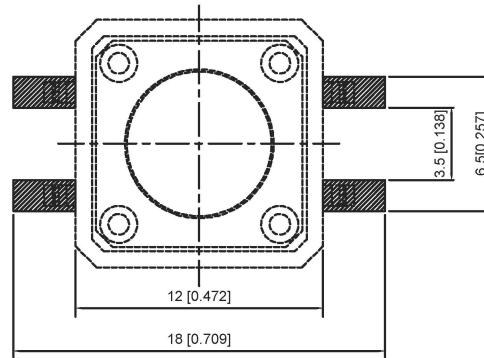
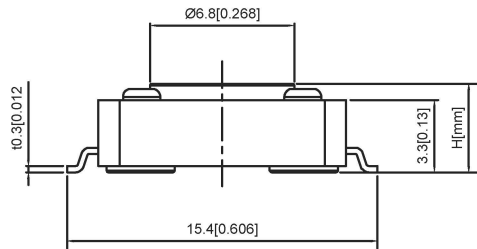


CIRCUIT DIAGRAM



Code-x	H	Code-x	H
A	4.3	O	11.0
B	4.5	P	11.5
C	5.0	Q	12
D	5.5	R	12.5
E	6.0	S	13.0
F	6.5	T	13.5
G	7.0	U	14.0
H	7.5	V	15.0
I	8.0	W	15.5
J	8.5	X	16
K	9.0	Y	17
L	9.5	Z	18
M	10.0	19	19
N	10.5		

P.C.B MOUNTING PATTERN DIMENSION
The following soldering patterns are recommended for reflow soldering



SPECIFICATION

Contact Rating: 50mA, 12V DC
Contact Resistance: 100mΩ max
Insulation Resistance: 100mΩ min. 500V DC
Dielectric Strength: 250V AC/1minute
Travel: 0.25mm
Operating Temp: -30℃~+85℃
Storage Temp: -30℃~+80℃

PAPT NO	TS-1103S-X-X
Operating Force	B:160gf C:260gf
Height	Code-x

⑤	Terminal	—	4	Brass (0.30t)	Plating silvering	—
④	Contact	—	1	F.ag/Sus	Natural	—
③	Base	—	1	Pa46		—
②	Cover	—	1	Spcc	Plating Nickel	—
①	Keystake	—	1	Pa46		—
ITEM	PAPT NAMF	TER.NO	QTY	MATERIAL	FINISHING	REMARK

广东星坤科技股份有限公司

生效日期

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UNSPECIFIED TOLERANCES

DSND		DATE		SCALE: N/A	MODEL TYPE: TACT SWITCH		
DWN		DATE		VIEW: 	PART NO.:		
CHKD		DATE		UNIT: mm/in	DWG NO.:		
APPD		DATE		SIZE: A4	TS-1103S-X-X		
XKB INDUSTRIAL PRECISION CO.,LIMITED					WEIGHT	SHEET	REVISION
					1.0g	1/1	A0